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**PATENT****IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Application No.: 10/772,311                      Group Art Unit: 1732  
Filing Date: February 6, 2004              Examiner: Lee, Edmund H.  
Applicant: Sang-Hyeop LEE et al.  
Title: MOLDING METHOD AND MOLD FOR ENCAPSULATING  
BOTH SIDES OF PCB MODULE WITH WAFER LEVEL  
PACKAGE MOUNTED PCB  
Attorney Docket: 2557-000220/US

Customer Service Window  
Randolph Building  
401 Dulany Street  
Alexandria, VA 22314  
**Mail Stop Amendment**

January 6, 2009

**AMENDMENT UNDER 37 C.F.R. §1.111**

Sir:

In response to the non-Final Office Action mailed October 8, 2008, the following amendments and remarks are respectfully submitted in connection with the above-identified application.

**Amendments to the Claims** begin on page 2 of this Amendment.

**Remarks** begin on page 7 of this Amendment.

	Claims remaining after Amendment		Highest number previously paid for		Present extra
<b>Total</b>	9	-	20	=	0
<b>Independent</b>	2	-	3	=	0